

**Lecture 31 - The "Short"
Metal-Oxide-Semiconductor Field-Effect
Transistor (*cont.*)**

April 25, 2007

Contents:

1. Short-channel effects (*cont.*)

Reading assignment:

P. K. Ko, "*Approaches to Scaling.*"

Key questions

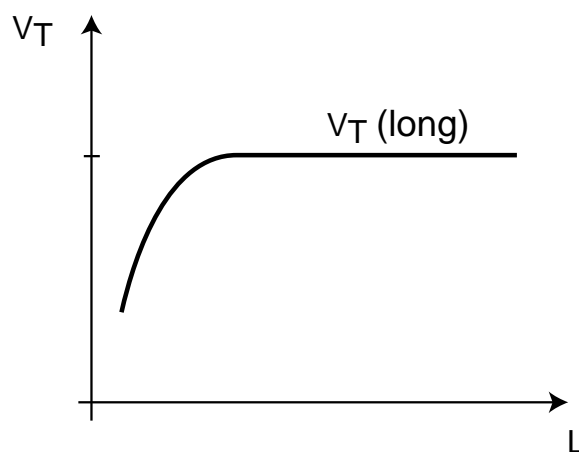
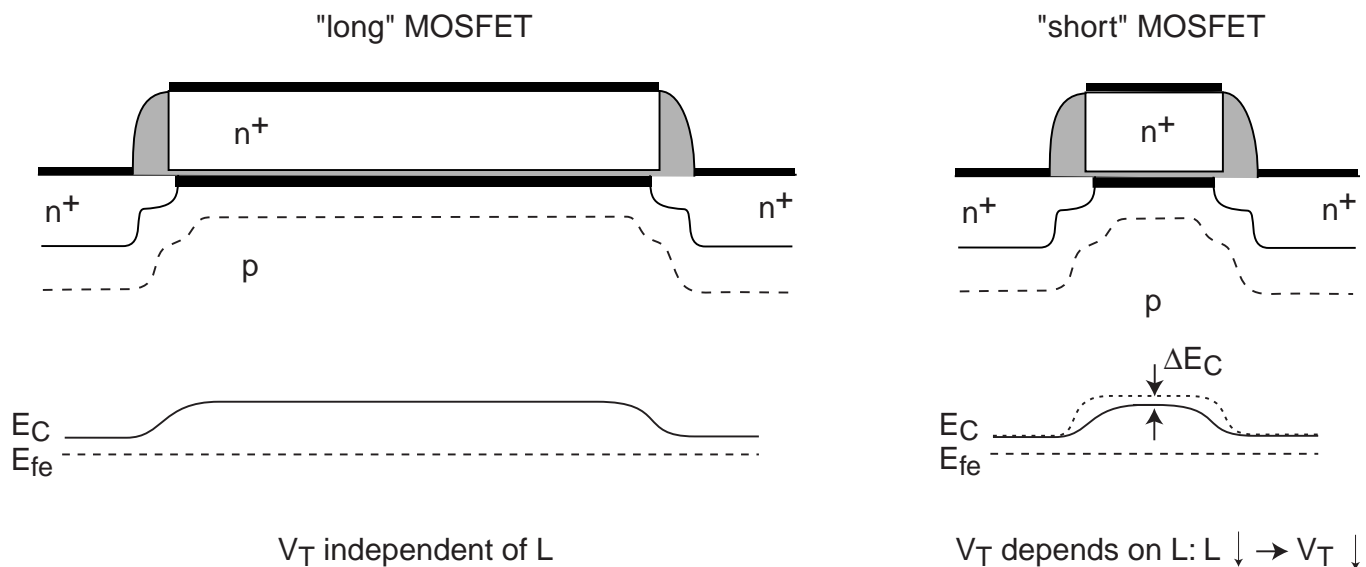
- Why does the threshold voltage seem to depend on the gate length of a MOSFET?
- Why does the threshold voltage of a MOSFET seem to depend on V_{DS} ?

1. Short-channel effects (*cont.*)

□ V_T dependence on L

Ideally, V_T does not depend on L , it only depends on x_{ox} and N_A .

If L is short enough, depletion regions of source and drain start overlapping underneath channel.

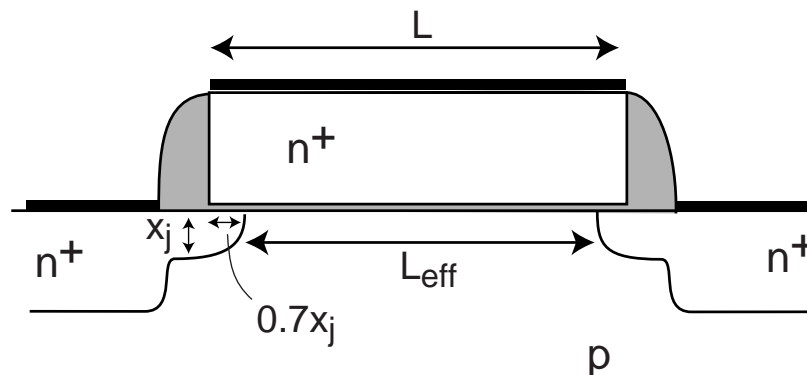


Complex 2D electrostatic problem:

- ΔV_T depends on the relative strength of the lateral electrostatics vs. the transversal electrostatics ("*electrostatic integrity*").
- The tighter the gate controls ϕ_s , the weaker ΔV_T dependence on L .

Key dependencies:

- $x_{ox} \downarrow \Rightarrow |\Delta V_T| \downarrow$
- $N_A \uparrow \Rightarrow |\Delta V_T| \downarrow$
- $x_j \downarrow \Rightarrow L_{eff} = L - 2 \times 0.7 x_j \uparrow \Rightarrow |\Delta V_T| \downarrow$



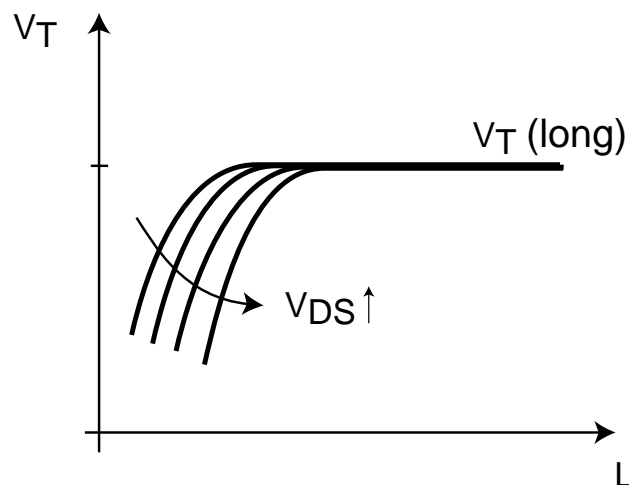
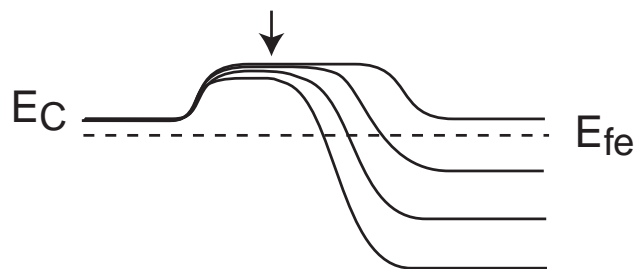
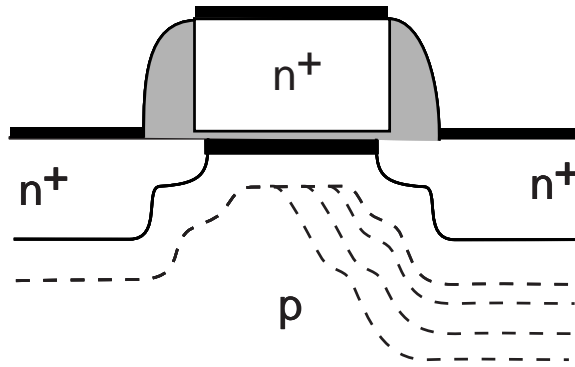
This is bad! long MOSFET: $V_T = f(x_{ox}, N_A)$
 short MOSFET: $V_T = f(x_{ox}, N_A, L, x_j)$

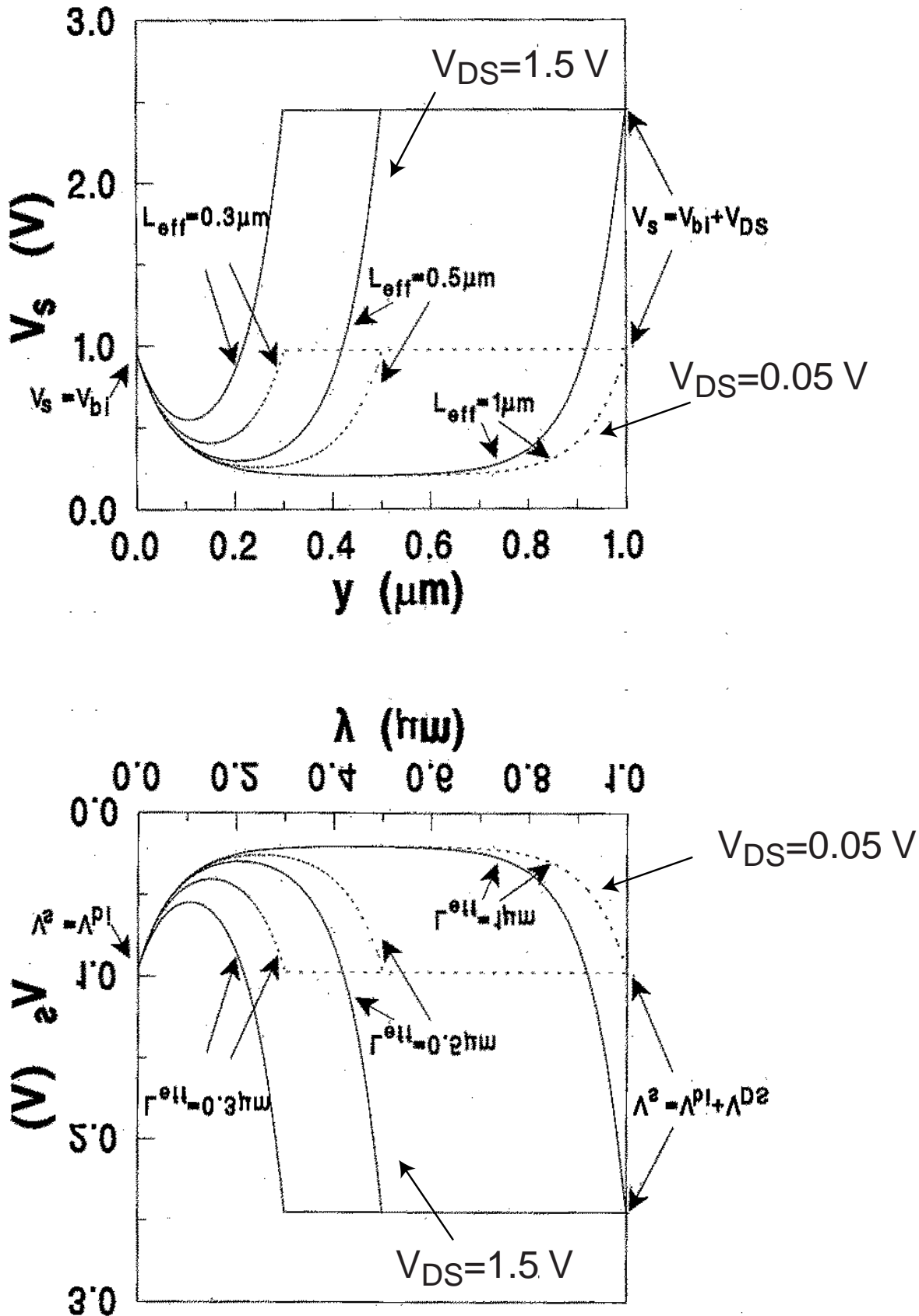
Most important consequence: V_T harder to control in manufacturing environment.

V_T model in next section.

□ Drain-induced barrier lowering (DIBL)

Depletion region associated with drain junction expands as $V_{DS} \uparrow \Rightarrow$ additional V_T shift.





Liu, Z.-H., C. Hu, J.-H. Huang, T.-Y. Chan, M.-C. Jeng, P. K. Ko, and Y. C. Cheng. "Threshold Voltage Model for Deep-Submicrometer MOSFET's." *IEEE Transactions on Electron Devices* 40, no. 1 (1993): 86-95. Copyright 1993 IEEE. Used with permission.

Simple analytical approximation to ΔV_T [Liu et al., TED 40, 86 (1993)]:

$$\begin{aligned}\Delta V_T &= [3(\phi_{bi} - \phi_{sth}) + V_{DS}]e^{-L_{eff}/\lambda} \\ &+ 2\sqrt{(\phi_{bi} - \phi_{sth})(\phi_{bi} - \phi_{sth} + V_{DS})}e^{-L_{eff}/2\lambda}\end{aligned}$$

with characteristic length:

$$\lambda = \sqrt{\frac{\epsilon_s}{\epsilon_{ox}}x_{ox}x_{dmax}}$$

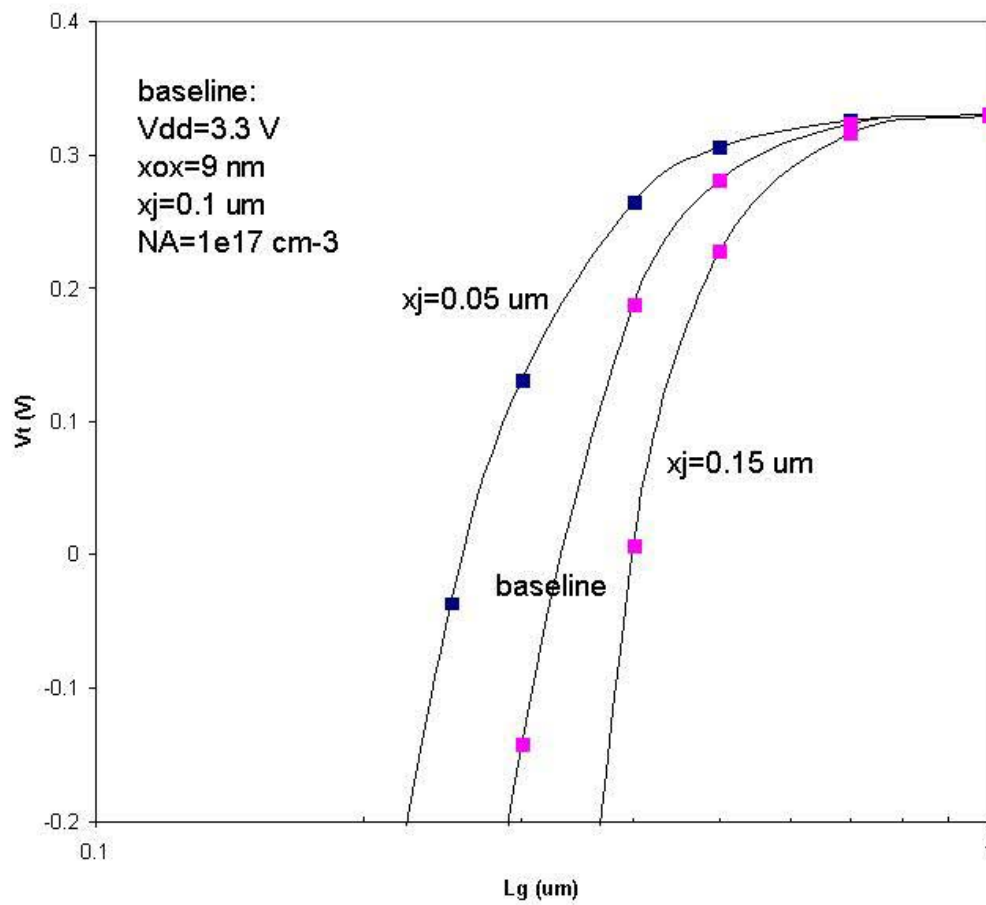
and

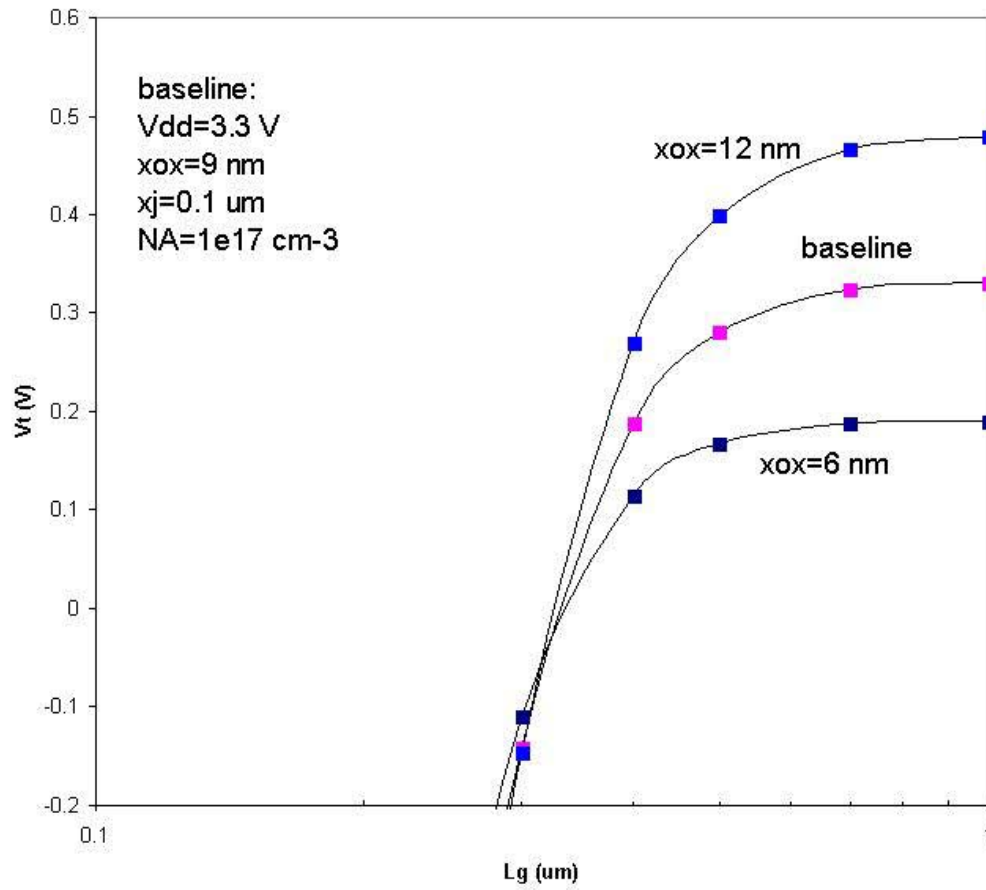
$$L_{eff} = L - 2 \times 0.7 x_j$$

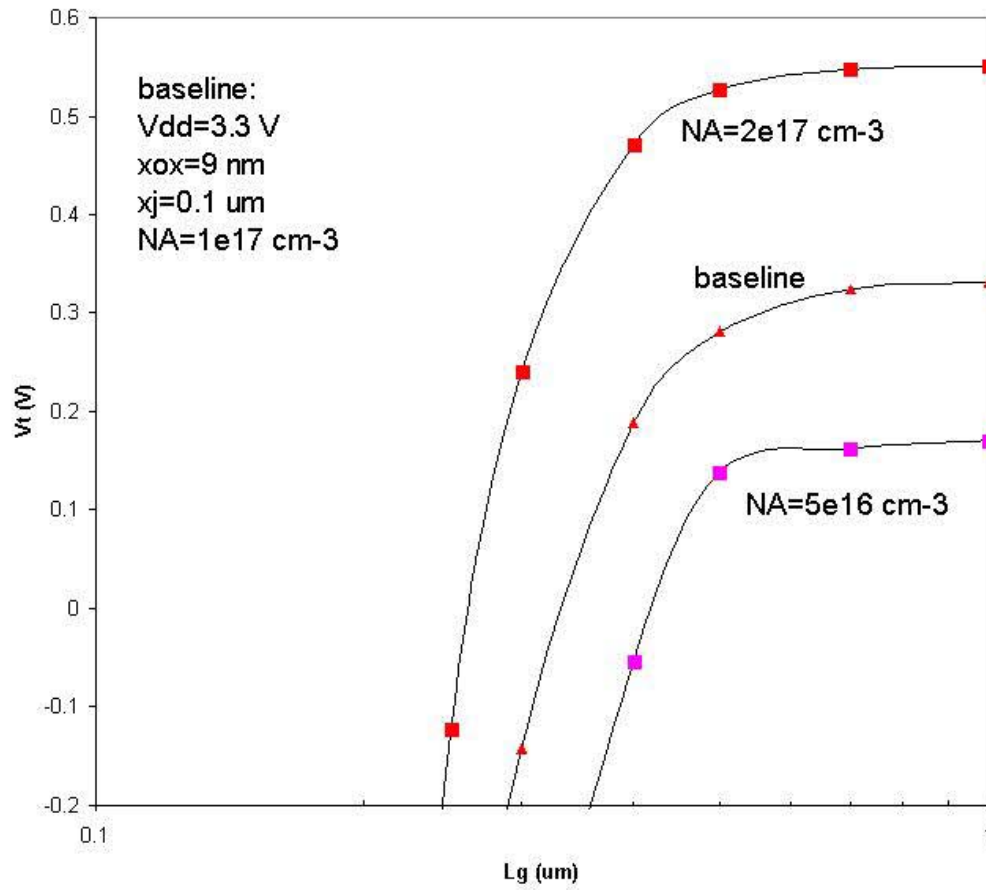
Quantification of DIBL:

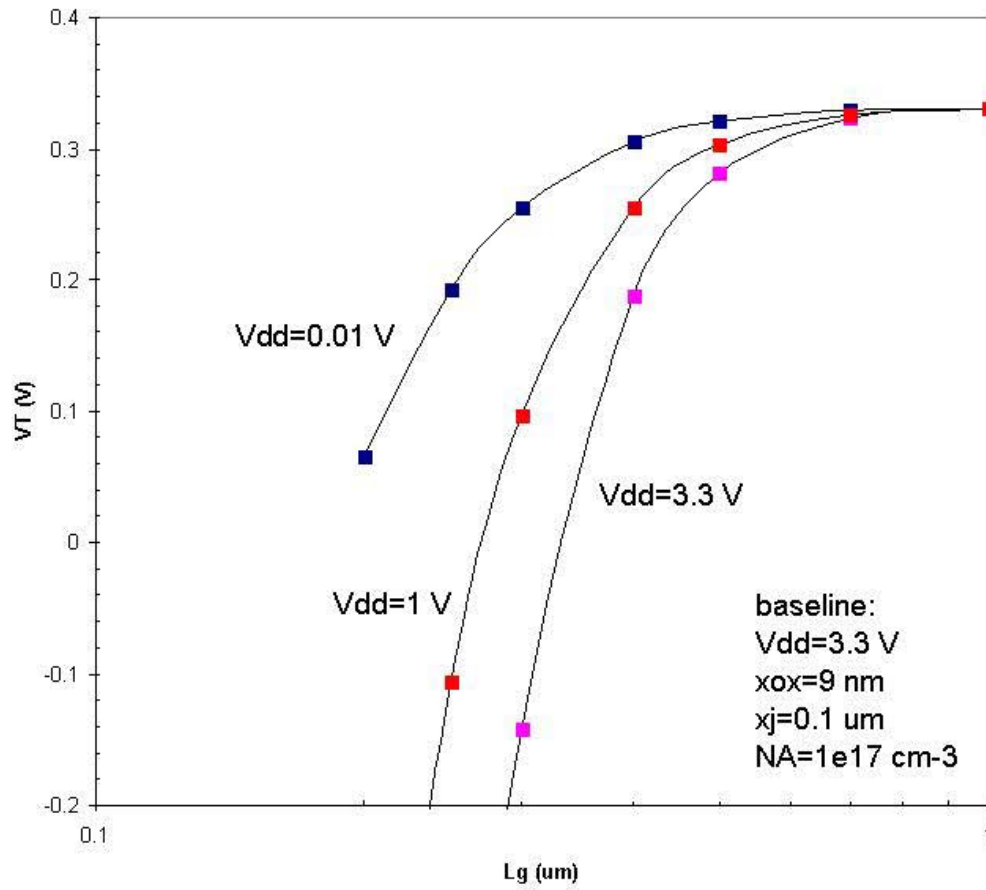
$$DIBL = \left| \frac{V_T(V_{DS} = V_{DD}) - V_T(V_{DS} = 0.1 V)}{V_{DD} - 0.1} \right| \text{ mV/V}$$

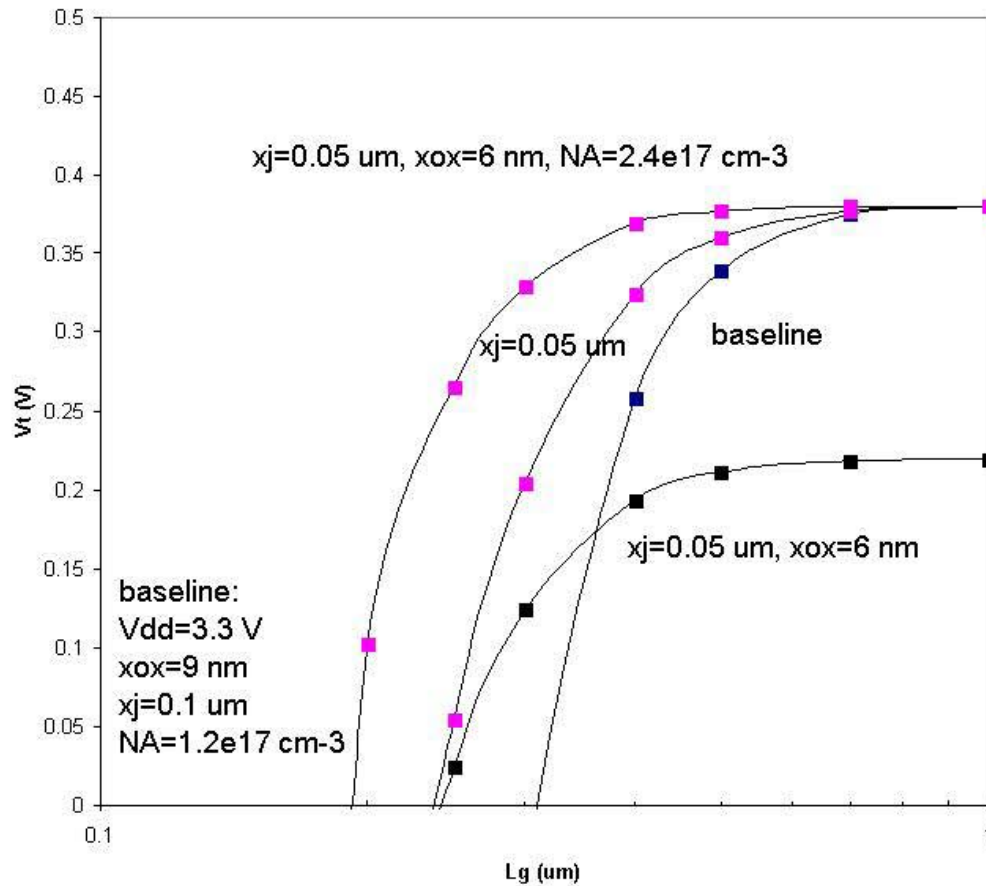
for a certain L device.











MOSFET design approach to manage DIBL:

1. shallower S/D junctions: $x_j = 0.1 \mu\text{m} \rightarrow 0.05 \mu\text{m}$
2. thinner gate oxide: $x_{ox} = 9 \text{ nm} \rightarrow 6 \text{ nm}$
3. increased body doping: $N_A = 1.2 \times 10^{17} \text{ cm}^{-3} \rightarrow 2.4 \times 10^{17} \text{ cm}^{-3}$

Comparison of simple model with 2D simulations:

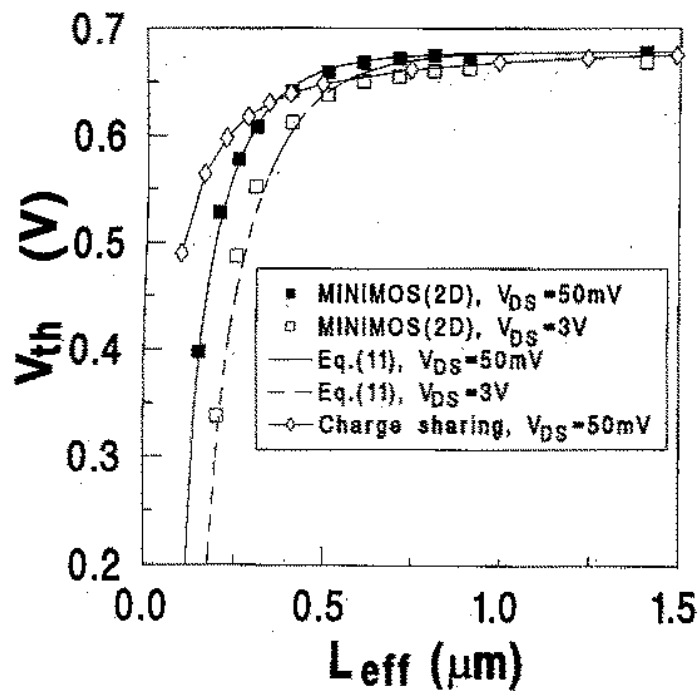


Fig. 4. A comparison of the V_{th} calculated using the charge sharing model, the two-dimensional numerical simulation (MINIMOS), and our model. The device parameters used are the same as those in Fig. 3.

Liu, Z.-H., C. Hu, J.-H. Huang, T.-Y. Chan, M.-C. Jeng, P. K. Ko, and Y. C. Cheng. "Threshold Voltage Model for Deep-Submicrometer MOSFET's." *IEEE Transactions on Electron Devices* 40, no. 1 (1993): 86-95. Copyright 1993 IEEE. Used with permission.

Comparison of simple model with experiments:

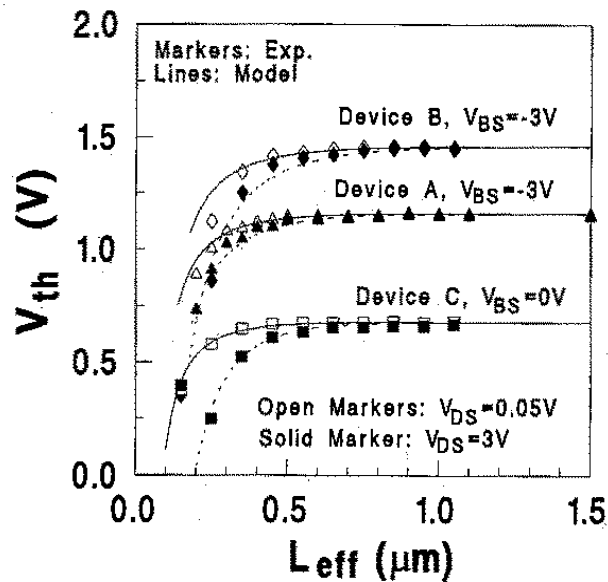


Fig. 5. Experimental and calculated threshold voltage versus effective channel length for non-LDD MOSFET's from different technologies, i.e., Device A: $T_{OX} = 55 \text{ \AA}$, $N_{SUB} = 3.6 \times 10^{17} \text{ cm}^{-3}$, $X_j = 0.25 \text{ μm}$, $l = 0.04 \text{ μm}$; Device B: $T_{OX} = 86 \text{ \AA}$, $N_{SUB} = 1.5 \times 10^{17} \text{ cm}^{-3}$, $X_j = 0.2 \text{ μm}$, $l = 0.05 \text{ μm}$; and Device C: $T_{OX} = 156 \text{ \AA}$, $N_{SUB} = 4 \times 10^{16} \text{ cm}^{-3}$, $X_j = 0.2 \text{ μm}$, $l = 0.09 \text{ μm}$.

Liu, Z.-H., C. Hu, J.-H. Huang, T.-Y. Chan, M.-C. Jeng, P. K. Ko, and Y. C. Cheng. "Threshold Voltage Model for Deep-Submicrometer MOSFET's." *IEEE Transactions on Electron Devices* 40, no. 1 (1993): 86-95. Copyright 1993 IEEE. Used with permission.

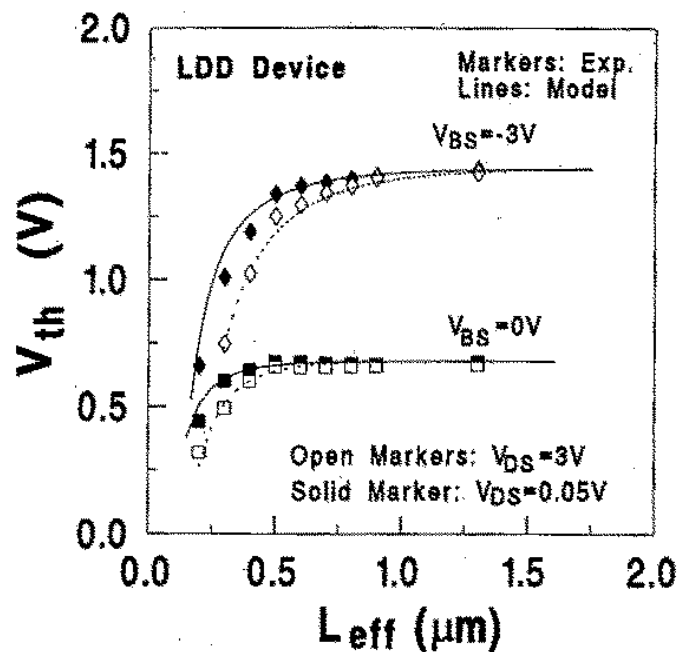


Fig. 7. Typical threshold voltage behavior for LDD device.

Liu, Z.-H., C. Hu, J.-H. Huang, T.-Y. Chan, M.-C. Jeng, P. K. Ko, and Y. C. Cheng. "Threshold Voltage Model for Deep-Submicrometer MOSFET's." *IEEE Transactions on Electron Devices* 40, no. 1 (1993): 86-95. Copyright 1993 IEEE. Used with permission.

DIBL also affects I_{off} : $V_{DS} \uparrow \Rightarrow V_T \downarrow \Rightarrow I_{off} \uparrow$

Figure removed due to copyright restrictions.

Shift of subthreshold curves.

Figure 5 on page 41 in

Fichtner, W., and H. W. Potzl. "MOS Modelling by Analytical Approximations." *International Journal of Electronics* 46, no. 1 (1979): 33-55.

Key conclusions

- V_T depends on L and V_{DS} :
 - For short L , V_T depends on L : $L \downarrow \Rightarrow V_T \downarrow$.
 - *Drain-induced barrier lowering (DIBL)*: impact of V_{DS} on V_T : $V_{DS} \uparrow \Rightarrow V_T \downarrow$.
- ΔV_T reflects relative strength of lateral electrostatics vs. transversal electrostatics ("*electrostatic integrity*").
- Electrostatic integrity improves if $x_{ox} \downarrow$, $N_A \uparrow$, $L \uparrow$, $x_j \downarrow$.
- DIBL problematic because:
 - V_T hard to control
 - $I_{off} \uparrow$